



Sponsorship Info

Oct 07 – 14, 2022

Hybrid - Shanghai

Embedded Systems Week (ESWEEK) is the premier event covering all aspects of hardware and software design for intelligent and connected computing systems. By bringing together four leading conferences (CASES, CODES+ISSS, EMSOFT and MEMOCODE), one symposium (NOCS) and several workshops and tutorials, ESWEEK allows attendees to benefit from a wide range of topics covering the state of the art in embedded systems research and development. ESWEEK provides high international visibility to its sponsors.

Covid-19 planning: Given the continued uncertainty, ESWEEK 22 is currently planned as a hybrid in-person/virtual event. Participants who are resident in China may attend in-person, the international community via a virtual platform.

Industrial Sponsorship Benefits

We invite Sponsors to contribute to ESWEEK 2022. ESWEEK offers different levels of sponsorship.

Sponsorship	Contribution	Recruitment Event	ESWEEK Webpage	Virtual Booth	Free Registration
Platinum	US \$2000	Yes	Yes	Yes	up to 5
Gold	US \$1000	Yes	Yes	Yes	up to 3
Silver	US \$500	Yes	Yes	No	up to 2
Bronze	US \$250	Yes	Yes	No	---

- **Recruitment Event** : All ESWEEK sponsors are entitled to participate in the recruitment event.
- **ESWEEK webpage** : All ESWEEK sponsor logo on the main ESWEEK webpage.
- **Event portal**: sponsor logos and rotating sponsor banners, company profiles and videos for promotion and advertisement in the web portal used during the event.
- **Industry Tutorials and Sessions**: A limited number of Industry Tutorials in the program can be accommodated for a sponsorship at the Gold or Platinum level.
- **Virtual exhibitor booth**: interactive virtual exhibitor space/booth and custom company web page in the interactive virtual platforms used during the event.

Conferences & Symposium



Int'l Conference on Compilers, Architecture, and Synthesis for Embedded Systems



Int'l Conference on Hardware/Software Codesign and System Synthesis



Int'l Conference on Embedded Software



Int'l Conference on Formal Methods and Models for System Design



International Symposium on Networks-on-Chip

Sponsoring Societies



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